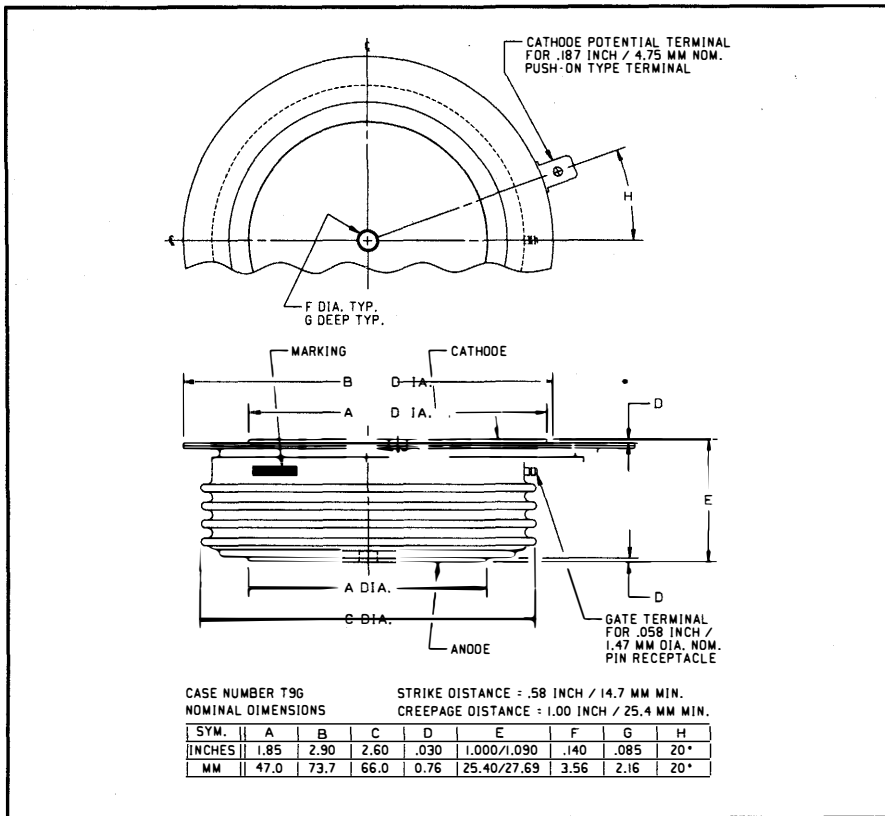




C451 (Outline Drawing)



C451 Phase Control SCR
1500 Amperes Average, 2400 Volts

Description:

Powerex Silicon Controlled Rectifiers (SCR) are designed for phase control applications. These are all-diffused, Press-Pak, hermetic Pow-R-Disc devices employing the field proven amplifying gate.

Features:

- ☐ Low On-State Voltage
- ☐ High di/dt Capability
- ☐ High dv/dt Capability
- ☐ Hermetic Packaging
- ☐ Excellent Surge and I^2t Ratings

Applications:

- ☐ Power Supplies
- ☐ Motor Control
- ☐ VAR Generators

Ordering Information:

Select the complete five or six digit part number you desire from the table, i.e. C451LD is a 2400 Volt, 1500 Ampere Phase Control SCR.

Type	Voltage		Current
	V_{DRM} V_{RRM}	Code	
C451	1400	PD	1500
	1600	PM	
	1800	PN	
	2000	L	
	2200	LB	
	2400	LD	

Absolute Maximum Ratings

Characteristics	Symbol	C451	Units
Non-repetitive Transient Peak Reverse Voltage	V_{RSM}	$V_{RRM} + 100V$	Volts
RMS On-state Current, $T_C = 64^\circ C$	$I_{T(rms)}$	2350	Amperes
Average Current 180° Sine Wave, $T_C = 64^\circ C$	$I_{T(av)}$	1500	Amperes
RMS On-state Current, $T_C = 55^\circ C$	$I_{T(rms)}$	2590	Amperes
Average Current 180° Sine Wave, $T_C = 55^\circ C$	$I_{T(av)}$	1650	Amperes
Peak One Cycle Surge On-state Current (Non-repetitive) 60Hz	I_{tsm}	23000	Amperes
Peak One Cycle Surge On-state Current (Non-repetitive) 50Hz	I_{tsm}	20800	Amperes
Critical Rate-of-rise of On-state Current (Non-repetitive)	di/dt	400	A/ μ sec
Critical Rate-of-rise of On-state Current (Repetitive)	di/dt	75	A/ μ sec
I^2t (for Fusing) for One Cycle, 60Hz	I^2t	2.2×10^6	A ² sec
Peak Gate Power Dissipation	P_{GM}	200	Watts
Average Gate Power Dissipation	$P_{G(av)}$	5	Watts
Operating Temperature	T_j	-40 to +125°C	°C
Storage Temperature	T_{stg}	-40 to +150°C	°C
Approximate Weight		1	lb.
		454	g
Mounting Force		5500 to 6000	lb.
		2450 to 2670	kg.

Electrical Characteristics, $T_j = 25^\circ\text{C}$ Unless Otherwise Specified

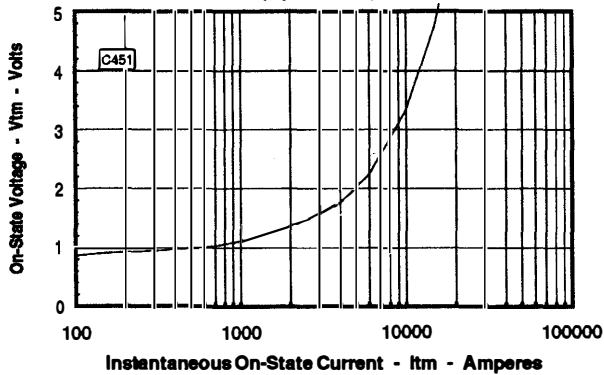
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Repetitive Peak Reverse Leakage Current	I_{RRM}	$T_j = 125^\circ\text{C}$, $V_R = V_{RRM}$			45	mA
Repetitive Peak Forward Leakage Current	I_{DRM}	$T_j = 125^\circ\text{C}$, $V_D = V_{DRM}$			45	mA
Peak On-state Voltage	V_{TM}	$I_{TM} = 3000\text{A}$ Peak Duty Cycle < 0.1%			1.7	Volts
Threshold Voltage, Low-level	$V_{(TO)1}$	$T_j = 125^\circ\text{C}$, $I = 15\%$, $I_{T(av)}$ to $\pi I_{T(av)}$			0.87956	Volts
Slope Resistance, Low-level	r_{T1}				0.2271	m Ω
Threshold Voltage, High-level	$V_{(TO)2}$	$T_j = 125^\circ\text{C}$, $I = \pi I_{T(av)}$ to I_{TSM}			0.59931	Volts
Slope Resistance, High-level	r_{T2}				0.2781	m Ω
V_{TM} Coefficients, Low-level		$T_j = 125^\circ\text{C}$, $I = 15\%$ $I_{T(av)}$ to $\pi I_{T(av)}$			$A_1 = 0.83982$ $B_1 = 4.972\text{E-}04$ $C_1 = 2.032\text{E-}04$ $D_1 = 0.002154$	
V_{TM} Coefficients, High-level		$T_j = 125^\circ\text{C}$, $I = \pi I_{T(av)}$ to I_{TSM}			$A_2 = 12.127$ $B_2 = -1.8090$ $C_2 = 1.429\text{E-}04$ $D_2 = 0.064436$	
Typical Delay Time	t_d	$I_T = 50\text{A}$, Gate = 20V, 20 Ω , 0.1 μsec Rise		0.7		μsec
Typical Turn-off Time	t_q	$T_j = 125^\circ\text{C}$, $I_T = 2000\text{A}$, $di_R/dt = 25\text{A}/\mu\text{sec}$ Reapplied $dv/dt = 200\text{V}/\mu\text{sec}$ Linear to 80% V_{DRM} , $V_R = 50\text{V}$, Gate = 0V, $R_{GK} = 100\Omega$		150		μsec
Minimum Critical dv/dt - Exponential to V_{DRM}	dv/dt	$T_j = 125^\circ\text{C}$	400			V/ μsec
Gate Trigger Current	I_{GT}	$T_j = 25^\circ\text{C}$, $V_D = 20V_{DC}$, $R_L = 3\Omega$			200	mA
Gate Trigger Voltage	V_{GT}	$T_j = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $V_D = 20\text{V}$, $R_L = 3\Omega$			5.0	Volts
Non-Triggering Gate Voltage	V_{GDM}	$T_j = 125^\circ\text{C}$, $V_D = V_{DRM}$, $R_L = 1000\Omega$			0.15	Volts
Peak Forward Gate Current	I_{GTM}				10	A
Peak Reverse Gate Voltage	V_{GRM}				5	Volts

Thermal Characteristics

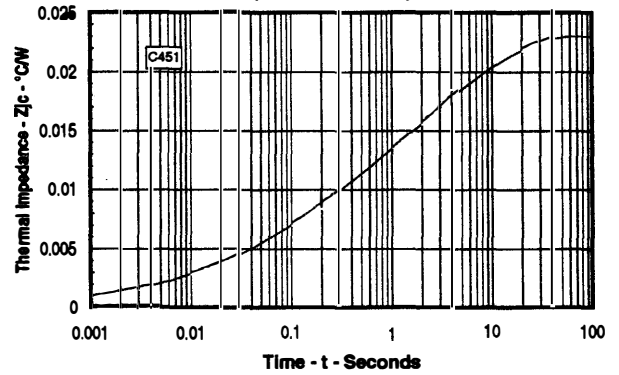
Maximum Thermal Resistance, Double Sided Cooling

Junction-to-Case	$R_{\theta(j-c)}$	0.025	$^\circ\text{C}/\text{W}$
Case-to-Sink	$R_{\theta(c-s)}$	0.0075	$^\circ\text{C}/\text{W}$

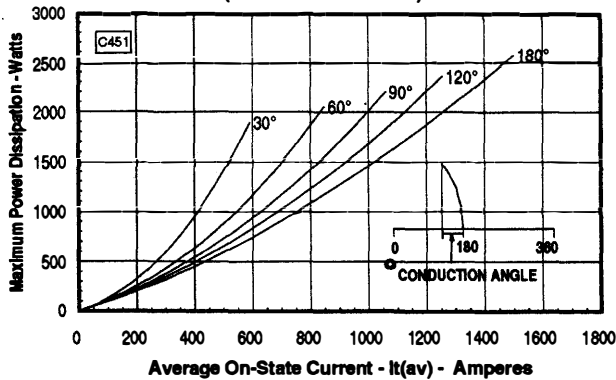
Maximum On-State Forward Voltage Drop
($T_J = 125^\circ\text{C}$)



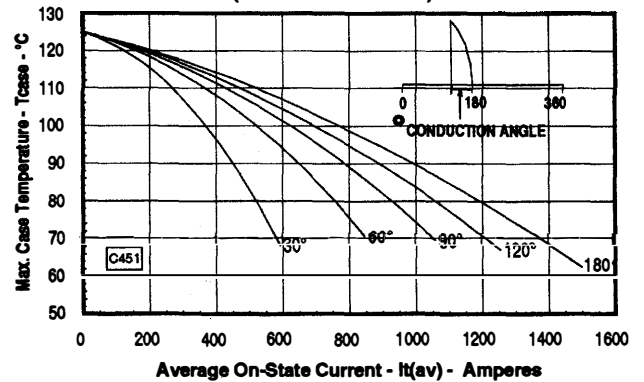
Maximum Transient Thermal Impedance
(Junction to Case)



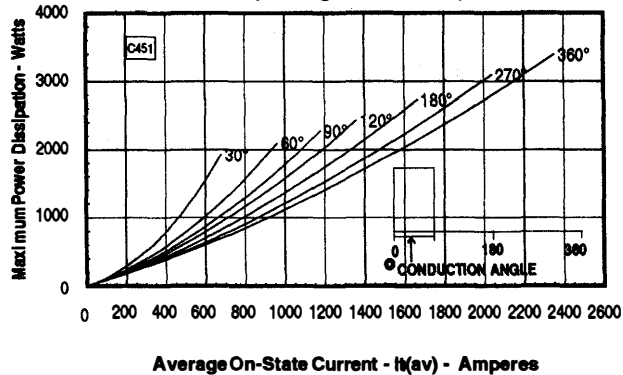
Maximum On-State Power Dissipation
(Sinusoidal Waveform)



Maximum Allowable Case Temperature
(Sinusoidal Waveform)



Maximum On-State Power Dissipation
(Rectangular Waveform)



Maximum Allowable Case Temperature
(Rectangular Waveform)

